T-1(3mm) BI-COLOR INDICATOR LAMP

Part Number: WP937EGW

High Efficiency Red Green

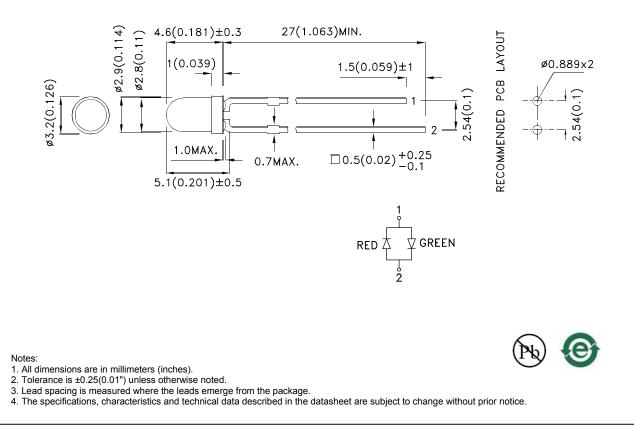
Features

- Uniform light output.
- Low power consumption.
- Long life solid state reliability.
- RoHS compliant.

Descriptions

- The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.
- The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



REV NO: V.7A CHECKED: Allen Liu DATE: JAN/22/2015 DRAWN: Q.M.Chen PAGE: 1 OF 7 ERP: 1101008548

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Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA				Viewing Angle [1]
			Min. Typ. 6 14	201/2			
	List Efficience Ded (Oc A-D(O-D)		6 14	14	- 60°		
WP937EGW	High Efficiency Red (GaAsP/GaP)		*4	*10			
	Green (GaP)	White Diffused	6	14			
			*6	*14			

Notes:

1.01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2.Luminous intensity/ luminous Flux: +/-15%.
*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	High Efficiency Red Green	627 565		nm	I⊧=20mA	
λD [1]	Dominant Wavelength	High Efficiency Red Green	617 568		nm	I⊧=20mA	
Δλ1/2	Spectral Line Half-width	High Efficiency Red Green	45 30		nm	I⊧=20mA	
С	Capacitance	High Efficiency Red Green	15 15		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	High Efficiency Red Green	2 2.2	2.5 2.5	V	IF=20mA	

Notes:

1.Wavelength: +/-1nm. 2.Forward Voltage: +/-0.1V. 3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

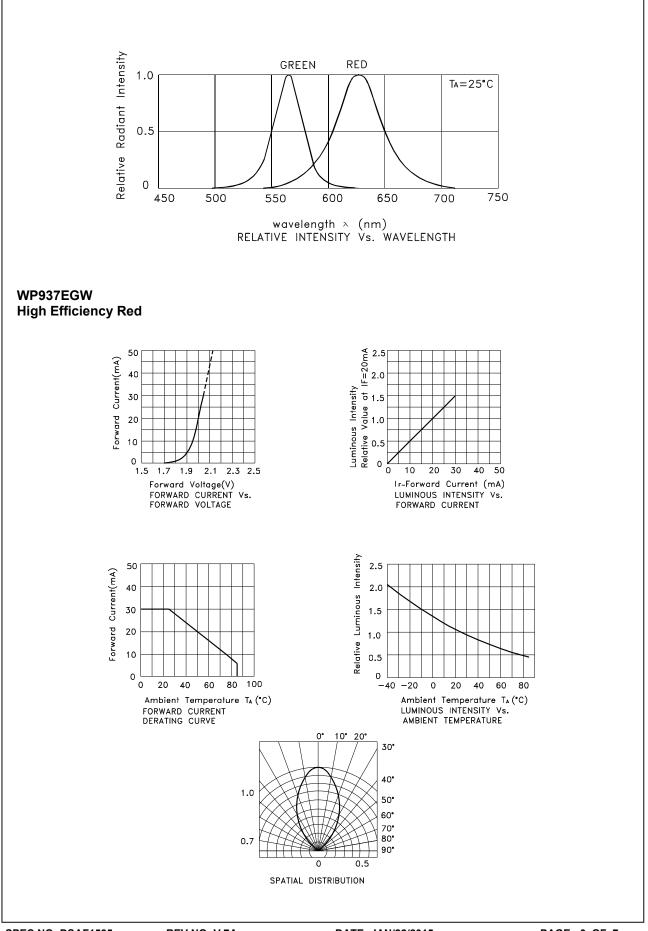
Parameter	High Efficiency Red	Green	Units			
Power dissipation	75	62.5	mW			
DC Forward Current	30	25	mA			
Peak Forward Current [1]	160	140	mA			
Operating / Storage Temperature	-40°C To +85°C					
Lead Solder Temperature [2]	260°C For 3 Seconds					
Lead Solder Temperature [3]	260°C For 5 Seconds					

Notes:

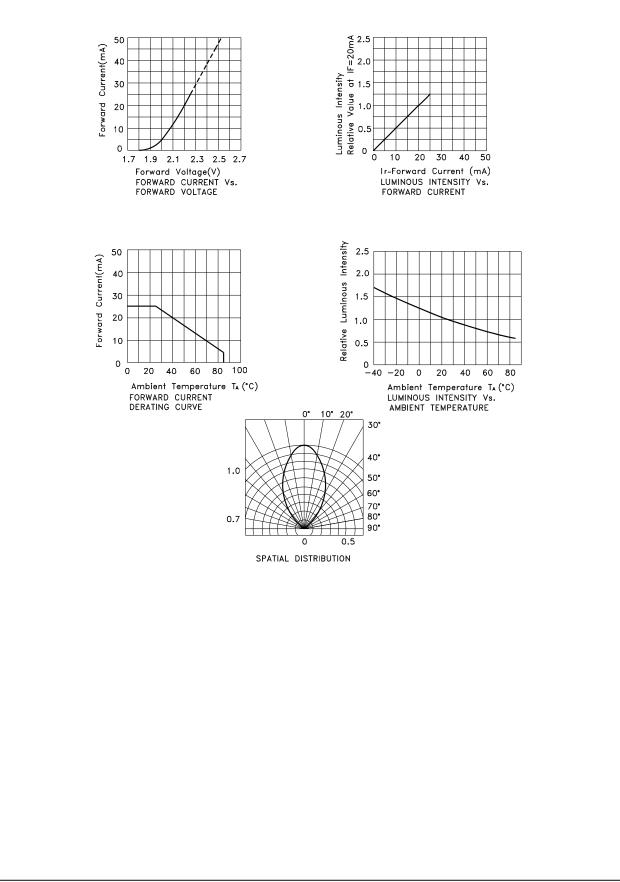
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

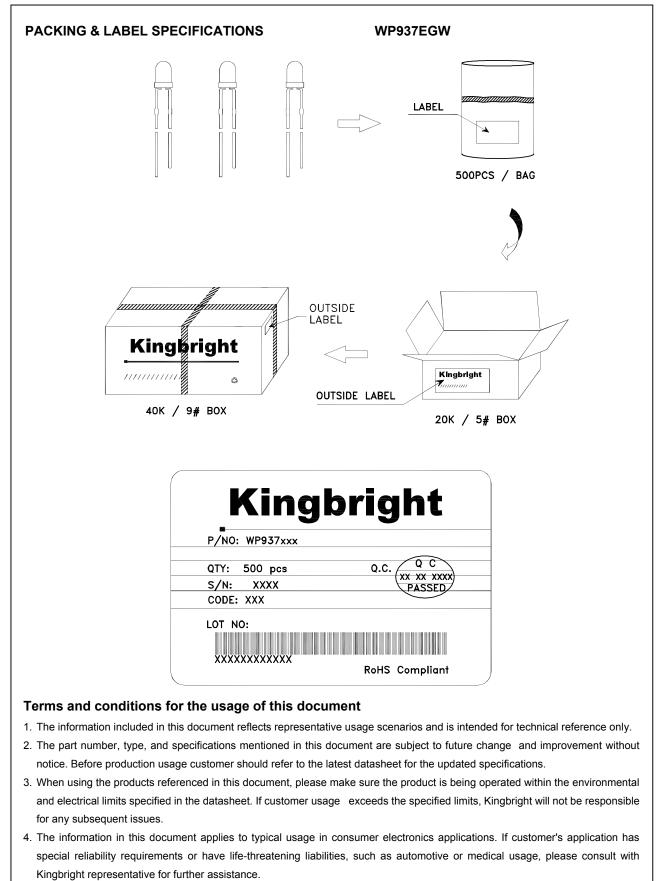
2. 2mm below package base.

3. 5mm below package base.



Green





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- 6. All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

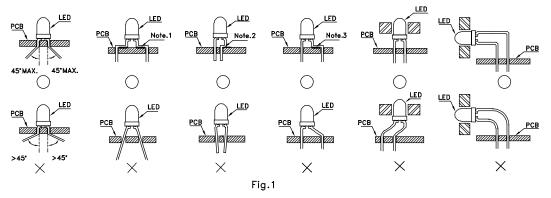
DATE: JAN/22/2015 DRAWN: Q.M.Chen

PRECAUTIONS

1. Storage conditions:

a.Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.

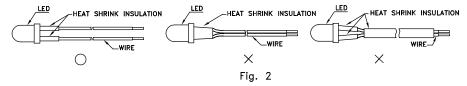
- b.LEDs should be stored with temperature $\leq 30^{\circ}$ C and relative humidity < 60%.
- c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.
- 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



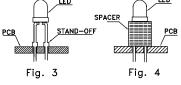
" \bigcirc " Correct mounting method "imes" Incorrect mounting method

Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

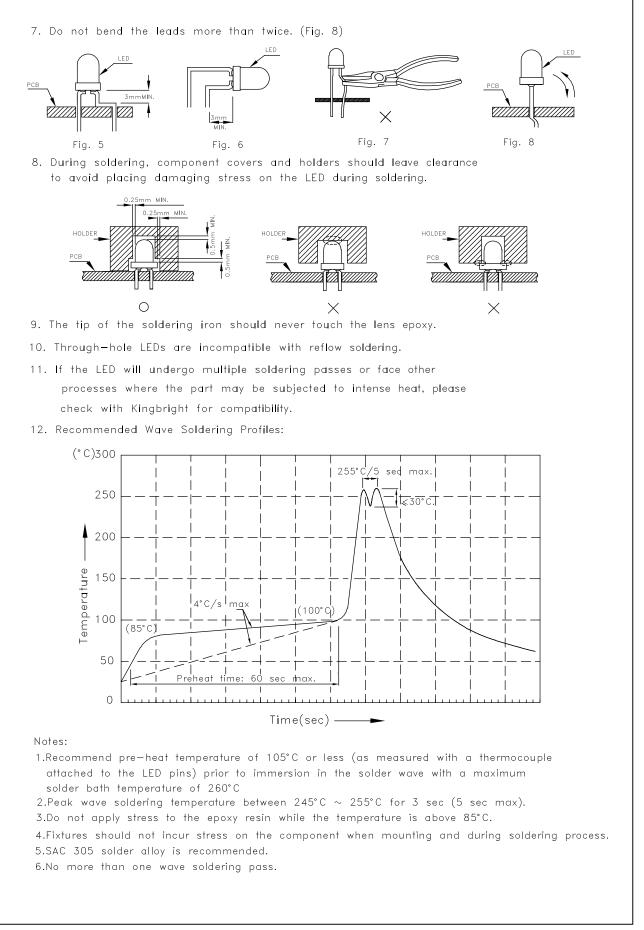
3. When soldering wires to the LED, each wire joint should be separately insulated with heat-shrink tube to prevent short-circuit contact. Do not bundle both wires in one heat shrink tube to avoid pinching the LED leads. Pinching stress on the LED leads may damage the internal structures and cause failure. (Fig. 2)



4. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 5. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 6. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)



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